

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	966	257/783.ccls. and @pd<"20050208"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 12:14
L2	74	257/783.ccls. and @pd>"20050208"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 12:16
L3	517	257/778,782,731,774.ccls. and @pd>"20050208"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 12:39
L4	1290	package same (opening orifice hole through-hole) same adhesive	US-PGPUB	OR	ON	2005/09/17 12:40
L5	522	package same (opening orifice hole through-hole) same adhesive same (chip die circuit)	US-PGPUB	OR	ON	2005/09/17 12:41
L6	82	(package same (opening orifice hole through-hole) same adhesive same (chip die circuit)).clm.	US-PGPUB	OR	ON	2005/09/17 12:41
S1	963	257/783.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 12:14
S2	965	257/7\$.ccls. and (FR-4 (BT adj resin))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 07:58
S3	2	("20020158335").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/31 18:46
S4	10275	("257"/\$.ccls. "438"/\$.ccls.) and (orifice cavity opening) and bonding and package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/31 19:25
S5	9452	("257"/\$.ccls. "438"/\$.ccls.) and (orifice cavity opening) and bonding and package and (chip die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/16 17:18

S6	8767	("257"/\$.ccls.) and (orifice cavity opening) and bonding and package and (chip die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/31 19:26
S7	4210	("257"/7\$.ccls.) and (orifice cavity opening) and bonding and package and (chip die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/31 19:27
S8	2992	("257"/7\$.ccls.) and ((orifice cavity opening) same (die chip)) and bonding and package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/31 22:10
S10	2375	("257"/6\$.ccls.) and ((orifice cavity opening) same (die chip)) and bonding and package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/01 12:07
S11	34	((("5376588") or ("5397921") or ("5728606") or ("5409865") or ("5663530") or ("5773884") or ("6127735") or ("5835355") or ("6549413") or ("6051273") or ("6479903") or ("6084297") or ("5835355") or ("6002169") or ("20020158335") or ("6488806") or ("6734535") or ("6472762"))).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/16 13:39
S12	9663	("257"/\$.ccls. "438"/\$.ccls.) and (orifice cavity opening) and bonding and package and (chip die) and @pd<"20050208"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/16 17:40
S13	11453	("257"/\$.ccls. "438"/\$.ccls.) and (orifice cavity opening) and bonding and package and (chip die) and @pd<"20050208"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/16 17:18
S14	1127	("257"/\$.ccls. "438"/\$.ccls.) and (orifice cavity opening) and bonding and package and (chip die) and @pd>"20050208"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/16 17:41
S15	53	257/7\$.ccls. and ((FR-4 (BT adj resin)) with (cure\$1 adhesive))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 08:09

S16	3	(chip die) and core same (((FR-4 (BT adj resin)) with (cure\$1 adhesive))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 08:10
S17	8	(chip die) and member same (((FR-4 (BT adj resin)) with (cure\$1 adhesive))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 08:12
S18	72	(chip die) and substrate same (((FR-4 (BT adj resin)) with (cure\$1 adhesive))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 08:15
S19	75	(chip die IC (integrated adj circuit)) and substrate same (((FR-4 (BT adj resin)) with (cure\$1 adhesive))))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 08:24
S20	1497	(chip die IC (integrated adj circuit)) and (adhesive adj substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 08:24
S21	102	(chip die IC (integrated adj circuit)) and ((adhesive adj substrate) same (opening via through-hole hole))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 08:34
S22	421	(chip die IC (integrated adj circuit)) and ((adhesive near1 substrate) same (opening via through-hole hole))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 08:35
S23	1470	(chip die IC (integrated adj circuit)) and ((adhesive near2 substrate) same (opening via through-hole hole))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 09:02
S24	663	(chip die IC (integrated adj circuit)) and ((adhesive near2 (core member)) same (opening via through-hole hole))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/17 09:02